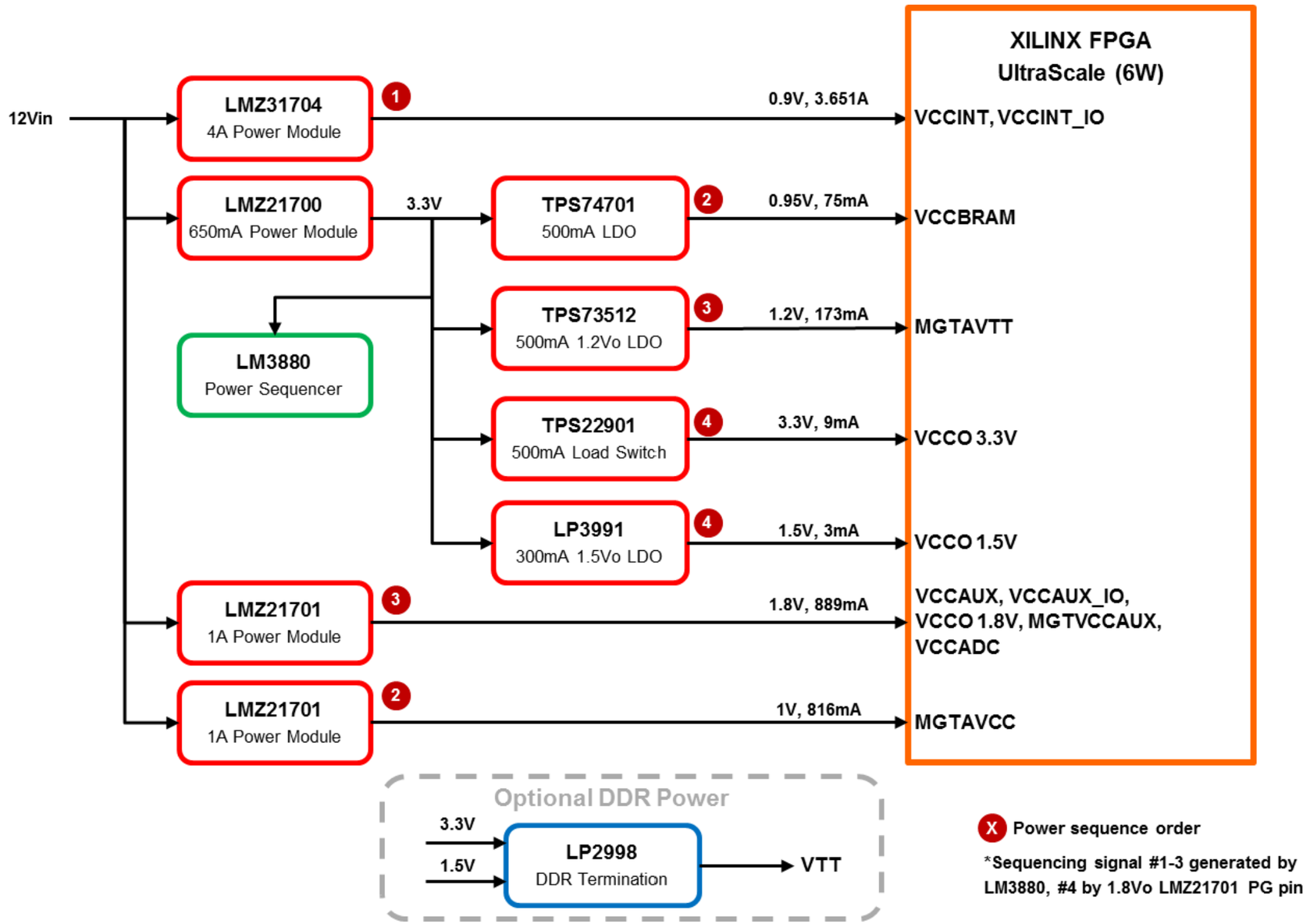
Revision History	
Revision	Notes



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 3/9/2015
TID #: N/A	Project Title: UltraScale 6W Power	
Number: PMP10630 Rev: 1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 4
Drawn By:	File: PMP10630_CoverSheet.SchDoc	Size: B
Engineer: X Fang	Contact: http://www.ti.com/support	

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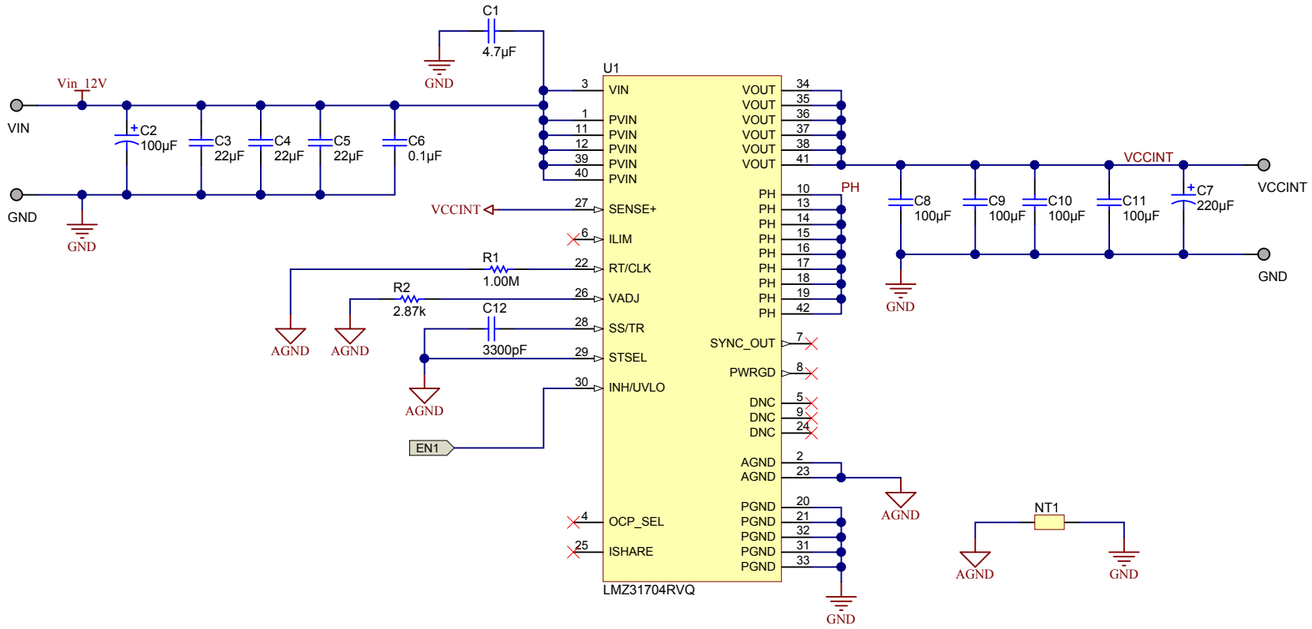
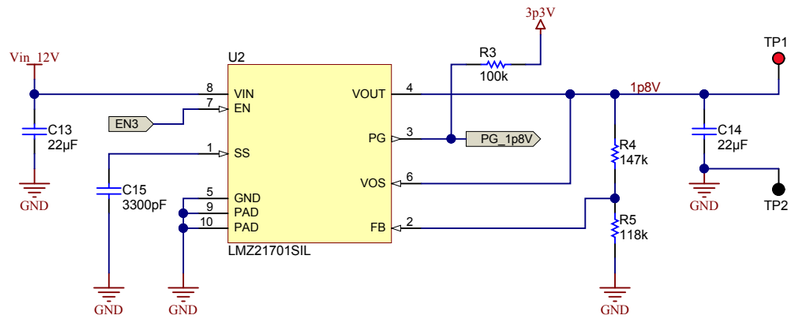
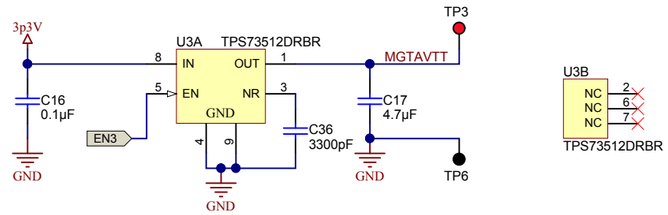
VCCINT, VCCINT_IO, 0.9V @ 3.651A



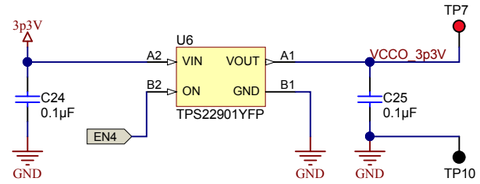
VCCAUX, VCCAUX_IO, VCCO 1.8V, MGTVCCAUX, VCCADC, 1.8V @ 889mA



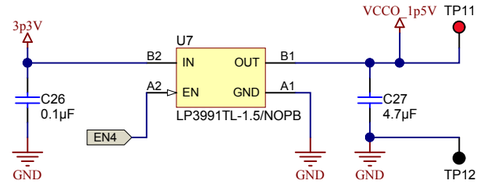
MGTAVTT, 1.2V @ 173mA



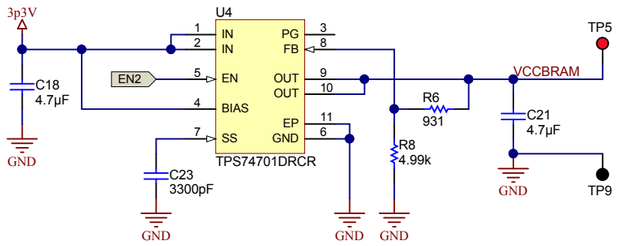
VCCO, 3.3V @ 9mA



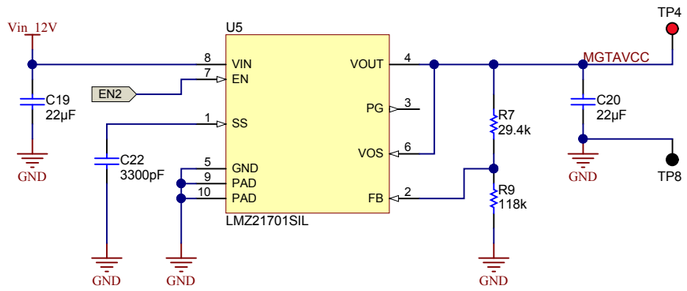
VCCO, 1.5V @ 3mA + DDR



VCCBRAM, 0.95V @ 75mA



MGTAVCC, 1V @ 816mA



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 3/9/2015
TID #: N/A	Project Title: UltraScale 6W Power	
Number: PMP10630 Rev: 1	Sheet Title: PMP10619 Main Power	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By:	File: PMP10630_Main Power.SchDoc	Size: B
Engineer: X Fang	Contact: http://www.ti.com/support	

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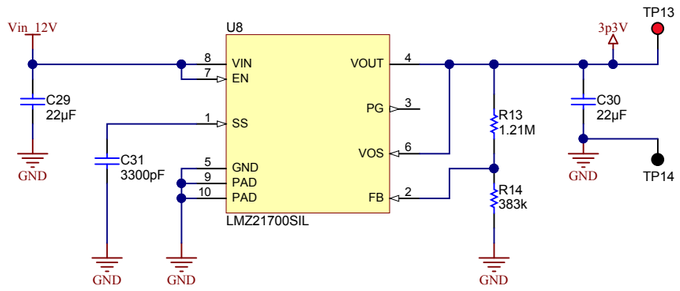
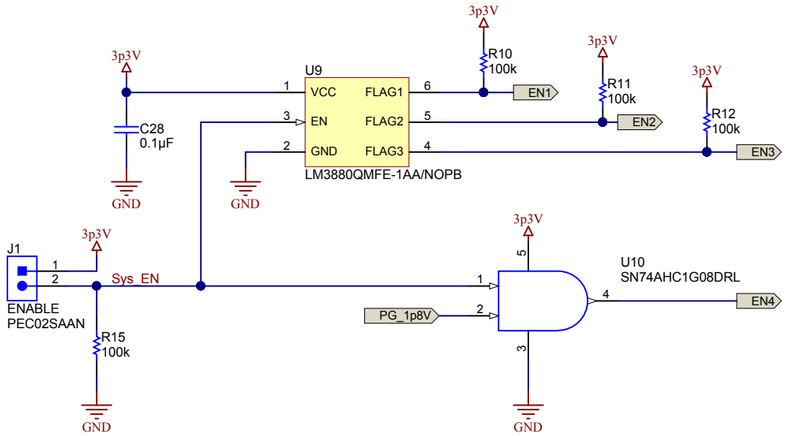
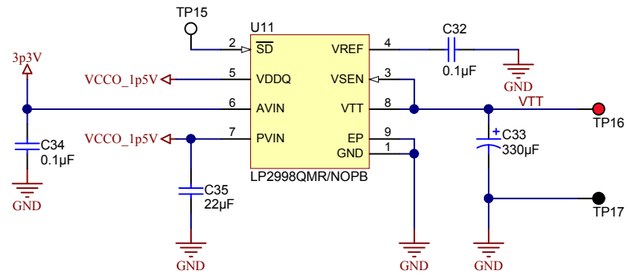
AUX Supply, 3.3V



Sequencer



DDR Termination



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 3/9/2015
TID #: N/A	Project Title: UltraScale 6W Power	
Number: PMP10630 Rev: 1	Sheet Title: PMP10619 Aux & Sequencer	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:	File: PMP10630_Aux & Sequencer.SchDoc	Size: B
Engineer: X Fang	Contact: http://www.ti.com/support	

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H1
NY PMS 440 0025 PH

H2
NY PMS 440 0025 PH

H3
NY PMS 440 0025 PH

H4
NY PMS 440 0025 PH

H5
1902C

H6
1902C

H7
1902C

H8
1902C

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: PMP10630
PCB Rev: B

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 3/9/2015
TID #: N/A	Project Title: UltraScale 6W Power	
Number: PMP10630 Rev: 1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 4 of 4
Drawn By:	File: PMP10630_EVM_Hardware.SchDoc	Size: B
Engineer: X Fang	Contact: http://www.ti.com/support	

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